



Material Content Data Sheet



Sales Product Name		IPB120N04S3-02		Issued		29. August 2013		
MA#		MA000361824						
Package		PG-TO263-3-2		Weight*		1468.74 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	12.237	0.83	0.83	8332	8332
leadframe	non noble metal	iron	7439-89-6	0.853	0.06		581	
	inorganic material	phosphorus	7723-14-0	0.256	0.02		174	
	non noble metal	copper	7440-50-8	851.691	57.99	58.07	579879	580634
wire	non noble metal	aluminium	7429-90-5	11.672	0.79	0.79	7947	7947
encapsulation	organic material	carbon black	1333-86-4	8.619	0.59		5868	
	plastics	epoxy resin	-	94.806	6.45		64549	
	inorganic material	silicondioxide	60676-86-0	471.155	32.08	39.12	320789	391206
leadfinish	non noble metal	tin	7440-31-5	9.657	0.66	0.66	6575	6575
plating	non noble metal	nickel	7440-02-0	0.228	0.02		156	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	156
solder	noble metal	silver	7440-22-4	0.189	0.01		129	
	non noble metal	tin	7440-31-5	0.151	0.01		103	
	non noble metal	lead	7439-92-1	7.224	0.49	0.51	4918	5150
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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